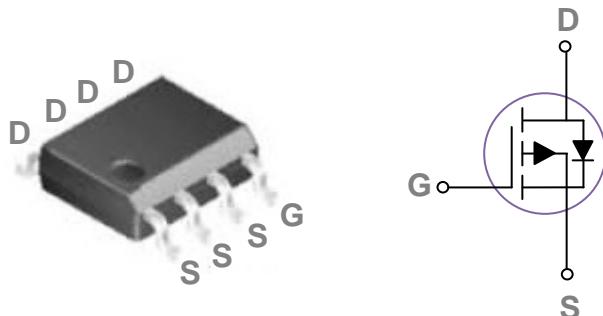


## 30V P-Channel MOSFETs

### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP-8 Pin Configuration



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	-10.5	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	-6.3	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-42	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	78.4	mJ
$I_{AS}$	Single Pulse Avalanche Current <sup>2</sup>	56	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	1.56	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.012	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient		80	$^\circ\text{C}/\text{W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-30			V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$		-0.03		$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$			-1	$\mu\text{A}$
		$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$			-10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$			$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-4\text{A}$		27	32	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-2\text{A}$		38	46	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-0.5	-1.0	-1.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient			4		$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{D}}=-3\text{A}$		9		S

**Dynamic and switching Characteristics**

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-5\text{A}$		8		nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>			3.3		
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>			2.3		
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_{\text{G}}=6\Omega$ $I_{\text{D}}=-1\text{A}$		4.6		ns
$T_r$	Rise Time <sup>2,3</sup>			14		
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>			34		
$T_f$	Fall Time <sup>2,3</sup>			18		
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$		757		pF
$C_{\text{oss}}$	Output Capacitance			122		
$C_{\text{rss}}$	Reverse Transfer Capacitance			88		

**Drain-Source Diode Characteristics and Maximum Ratings**

<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current			-10.5	A
$I_{\text{SM}}$	Pulsed Source Current				-42	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=-1\text{A}$ , $T_J=25^\circ\text{C}$			-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

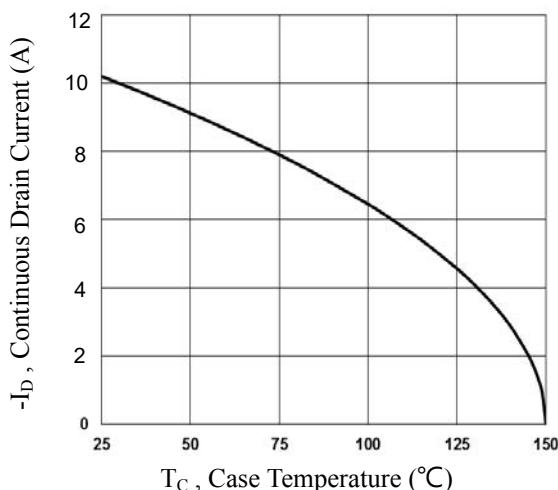


Fig.1 Continuous Drain Current vs. T<sub>C</sub>

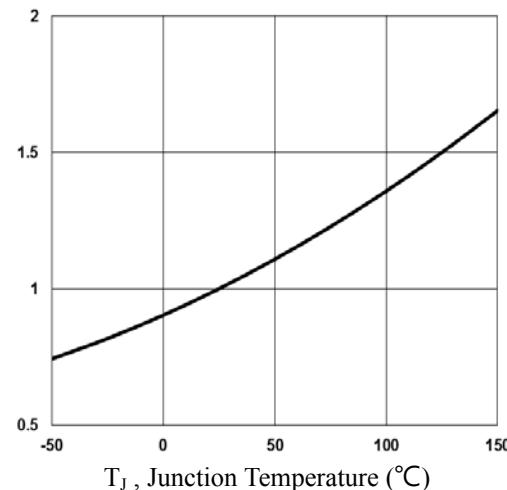


Fig.2 Normalized RDSON vs. T<sub>J</sub>

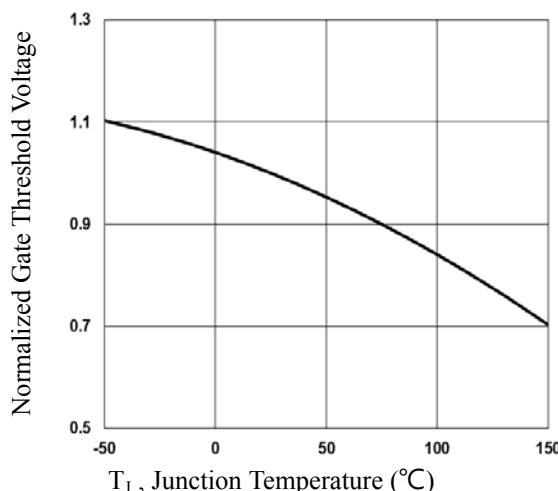


Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>

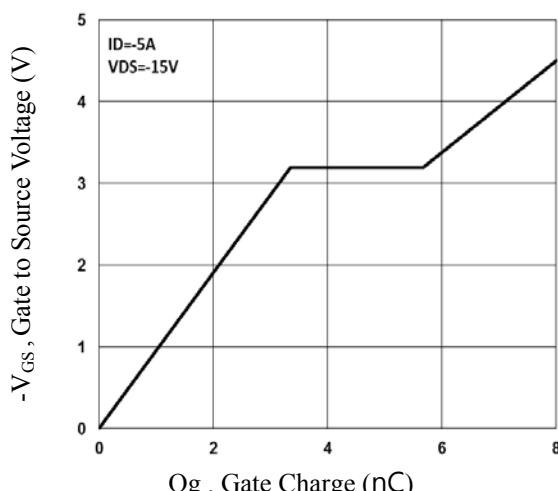


Fig.4 Gate Charge Waveform

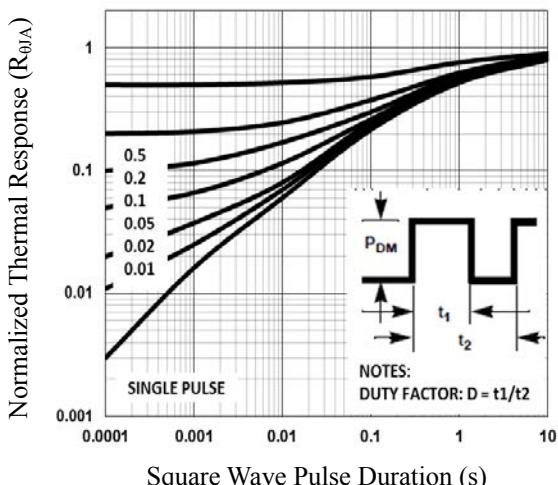


Fig.5 Normalized Transient Impedance

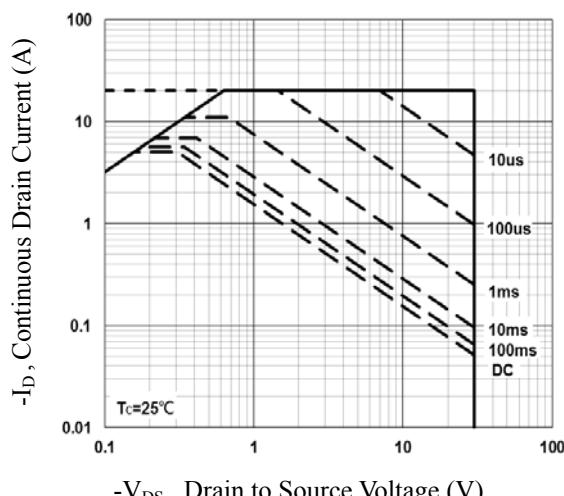


Fig.6 Maximum Safe Operation Area

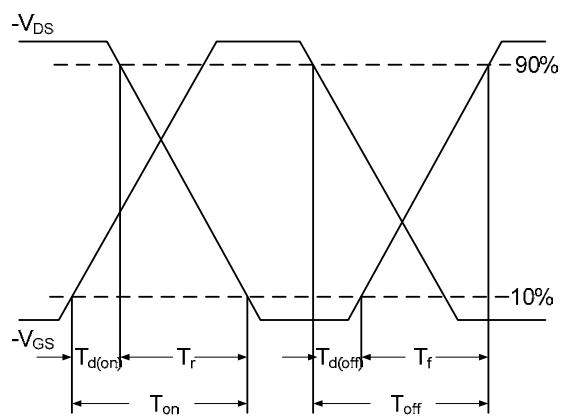


Fig.7 Switching Time Waveform

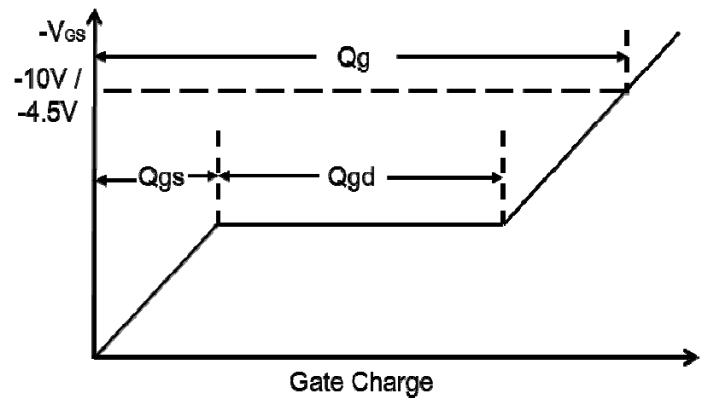
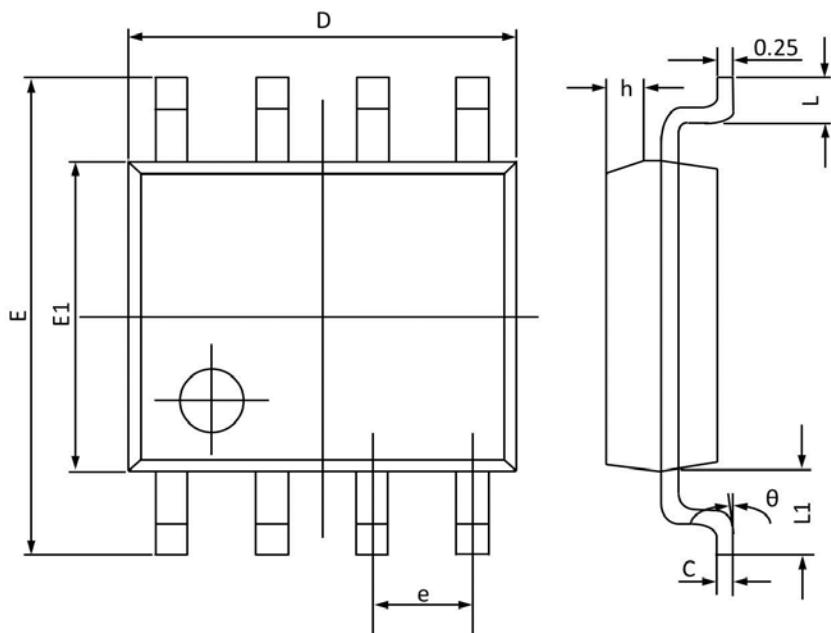


Fig.8 Gate Charge Waveform

## SOP-8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.150	0.900	0.045	0.035
A1	0.100	0.000	0.004	0.000
A2	1.050	0.900	0.041	0.035
b	0.500	0.300	0.020	0.012
c	0.150	0.080	0.006	0.003
D	3.000	2.800	0.118	0.110
E	1.400	1.200	0.055	0.047
E1	2.550	2.250	0.100	0.089
e	0.95 TYP.		0.037 TYP.	
e1	2.000	1.800	0.079	0.071
L	0.55 REF.		0.022 REF.	
L1	0.500	0.300	0.020	0.012
L2	0.25 TYP.		0.01 TYP.	
θ	8°	0°	8°	0°

V 1.0